

**AMENDMENT**

Please cancel claims 1-17 without prejudice.

Please enter the following new claims:

Claim 18 (newly added)      18. A curing light comprising:

    a wand adapted to be grasped by a human hand for use in positioning and manipulating the curing light,

    an elongate heat sink with a proximal end and a distal end, said proximal end being proximate said wand, said elongate heat sink having a longitudinal axis,

    a mounting platform located at said elongate heat sink distal end, said mounting platform being adapted to have a LED chip module,

    an LED chip module mounted on said mounting platform, said LED chip module including

        a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

        a well on said primary heat sink for mounting an LED chip,

        an LED chip mounted in said well,

        a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module, and

        a thermoelectric cooler located on said elongate heat sink, said thermoelectric cooler serving to assist in heat dissipation;

    wherein light emitted by said LED chip module is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis.

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Claim 19 (newly added)      19. A curing light as recited in claim 18 further comprising a thermoelectric cooler on said elongate heat sink.

Claim 20 (newly added)      20. A curing light as recited in claim 18 wherein light emitted by said LED chip module is emitted at an angle of about 90 degrees to said elongate heat sink longitudinal axis.

Claim 21 (newly added)      21. A curing light as recited in claim 18 further comprising at least one air vent on said wand.

Claim 22 (newly added)      22. A curing light as recited in claim 18 further comprising a plurality of insulators to insulate said elongate heat sink from said wand.

Claim 23 (newly added)      23. A curing light as recited in claim 18 wherein said wand has a housing and said elongate heat sink is located at least partially within said housing.

Claim 24 (newly added)      24. A curing light as recited in claim 22 further comprising an air space between said elongate heat sink and said wand.

Claim 25 (newly added)      25. A curing light comprising:  
an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis,  
a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,  
a well on said primary heat sink for mounting a semiconductor chip therein,  
a semiconductor chip mounted in said well,  
said primary heat sink being in heat communication with said elongate heat sink,  
said semiconductor chip being capable of emitting light useful in activating a light activated materials;  
wherein light emitted by said semiconductor chip is emitted at an angle of from about 30

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degrees to about 150 degrees to said elongate heat sink longitudinal axis.

Claim 26 (newly added)      26.      A curing light as recited in claim 25 further comprising a thermoelectric cooler on said elongate heat sink.

Claim 27 (newly added)      27.      A curing light as recited in claim 25 wherein light emitted by said semiconductor chip is emitted at an angle of about 90 degrees to said elongate heat sink longitudinal axis.

Claim 28 (newly added)      28.      A curing light as recited in claim 25 wherein said semiconductor chip is selected from the group consisting of light emitting diode chips, laser chips, light emitting diode chip array, diode laser chips, diode laser chip array, surface emitting laser chips, edge emitting laser chips, and VCSEL chips.

Claim 29 (newly added)      29.      A curing light as recited in claim 25 further comprising a lens over said well so that light emitted by said semiconductor chip is affected by said lens.

Claim 30 (newly added)      30.      A light comprising:  
        a secondary heat sink, said secondary heat sink serving to assist in heat dissipation, and said secondary heat sink having a longitudinal axis,  
        at least one semiconductor chip module capable of emitting useful light,  
        said semiconductor chip module including a primary heat sink,  
        said primary heat sink including a well,  
        said well having a semiconductor chip located therein,  
        said semiconductor chip module being in heat communication with said secondary heat sink so that light emitted by said semiconductor chip is drawn to said primary heat sink and thence to said secondary heat sink;  
        wherein light emitted by said chip is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis without use of any apparatus to change the direction of said light.

Claim 31 (newly added)      31.    A light as recited in claim 30 wherein said semiconductor chip is selected from the group consisting of light emitting diode chips, laser chips, light emitting diode chip array, diode laser chips, diode laser chip array, surface emitting laser chips, edge emitting laser chips, and VCSEL chips.

**CLAIM LISTING**

A complete listing of the claims is as follows:

Claims 1-17 (cancelled).

Claim 18 (newly added)      18. A curing light comprising:

    a wand adapted to be grasped by a human hand for use in positioning and manipulating the curing light,

    an elongate heat sink with a proximal end and a distal end, said proximal end being proximate said wand, said elongate heat sink having a longitudinal axis,

    a mounting platform located at said elongate heat sink distal end, said mounting platform being adapted to have a LED chip module,

    an LED chip module mounted on said mounting platform, said LED chip module including

        a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,

        a well on said primary heat sink for mounting an LED chip,

        an LED chip mounted in said well,

        a cover that provides protective covering for said LED chip and which permits light emitted by said LED chip to pass through it to provide usable light exiting from said light module, and

    a thermoelectric cooler located on said elongate heat sink, said thermoelectric cooler serving to assist in heat dissipation;

    wherein light emitted by said LED chip module is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis.

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Claim 22 (newly added)      22. A curing light as recited in claim 18 further comprising a plurality of insulators to insulate said elongate heat sink from said wand.

Claim 23 (newly added)      23. A curing light as recited in claim 18 wherein said wand has a housing and said elongate heat sink is located at least partially within said housing.

Claim 24 (newly added)      24. A curing light as recited in claim 22 further comprising an air space between said elongate heat sink and said wand.

Claim 25 (newly added)      25. A curing light comprising:  
an elongate heat sink with a proximal end and a distal end, said elongate heat sink having a longitudinal axis,  
a primary heat sink, said primary heat sink having a smaller mass than said elongate heat sink,  
a well on said primary heat sink for mounting a semiconductor chip therein,  
a semiconductor chip mounted in said well,  
said primary heat sink being in heat communication with said elongate heat sink,  
said semiconductor chip being capable of emitting light useful in activating a light activated materials;

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wherein light emitted by said semiconductor chip is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis.

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a secondary heat sink, said secondary heat sink serving to assist in heat dissipation, and said secondary heat sink having a longitudinal axis,  
at least one semiconductor chip module capable of emitting useful light,  
said semiconductor chip module including a primary heat sink,  
said primary heat sink including a well,  
said well having a semiconductor chip located therein,  
said semiconductor chip module being in heat communication with said secondary heat sink so that light emitted by said semiconductor chip is drawn to said primary heat sink and thence to said secondary heat sink;  
wherein light emitted by said chip is emitted at an angle of from about 30 degrees to about 150 degrees to said elongate heat sink longitudinal axis without use of any apparatus to

change the direction of said light.

Claim 31 (newly added)      31.      A light as recited in claim 30 wherein said semiconductor chip is selected from the group consisting of light emitting diode chips, laser chips, light emitting diode chip array, diode laser chips, diode laser chip array, surface emitting laser chips, edge emitting laser chips, and VCSEL chips.